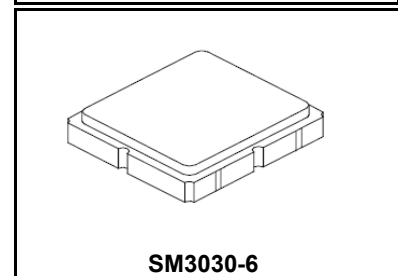


SF2361E

**428 MHz
SAW Filter**



- **Low-loss 428 MHz SAW Filter**
- **Designed for 50 ohm Source/Load**
- **Complies with Directive 2002/95/EC (RoHS)**
- **Moisture Sensitivity Level: 1**

Absolute Maximum Ratings

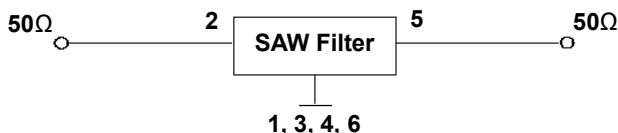
Rating	Value	Units
Input Power Level	+10	dBm
DC Voltage on any Non-ground Terminal	3	V
Operating Temperature Range	-40 to +85	°C
Storage Temperature Range in Tape and Reel	-40 to +85	°C
Maximum Soldering Profile, 5 cycles/10 seconds maximum	260	°C

Electrical Characteristics

Characteristic	Sym	Notes	Min	Typ	Max	Units
Center Frequency	fC			428		MHz
Insertion Loss (420 to 436 MHz)	IL			1.5	3.5	dB
Amplitude Ripple (420 to 436 MHz)				0.8	1.8	dB
Attenuation Reference level from 0 dB						
128 to 400 MHz			45	51		dB
470 to 728 MHz			45	49		
Temperature Coefficient of Frequency				-36		ppm/k
Case Style	SM3030-6 3.0 x 3.0 mm Nominal Footprint					
Lid Symbolization (Y=year, WW=week, S=shift) dot=pin 1 indicator	B25, <u>YWWS</u>					
Standard Reel Quantity	Reel Size 7 inch	500 Pieces/Reel				
	Reel Size 13 inch	3000 Pieces/Reel				

Electrical Connections

Connection	Terminals
Input	2
Output	5
Case Ground	All others

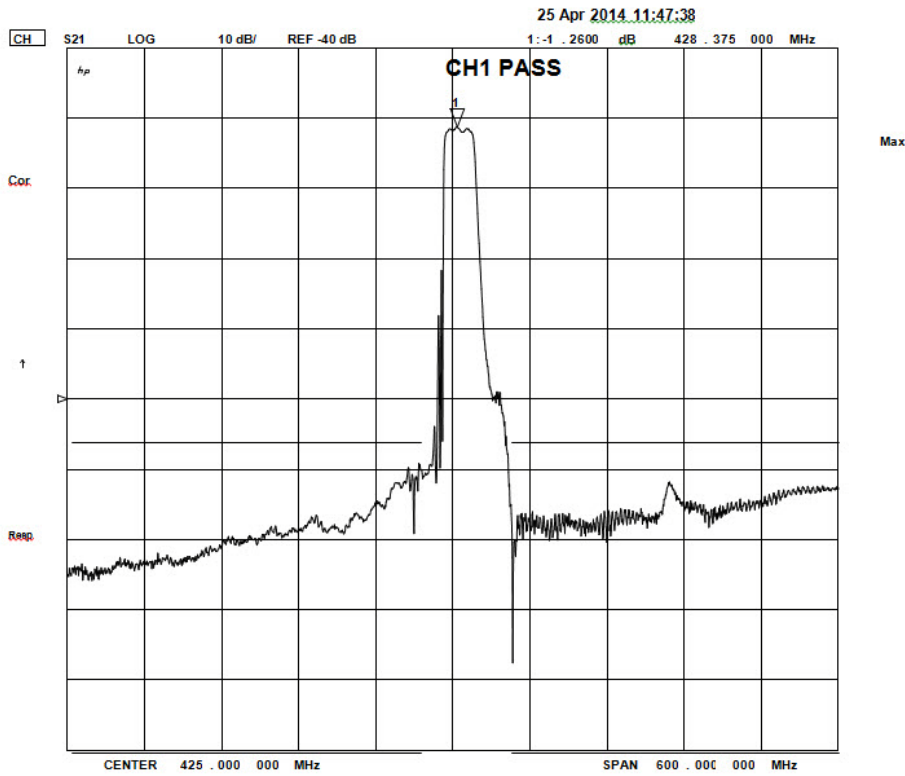
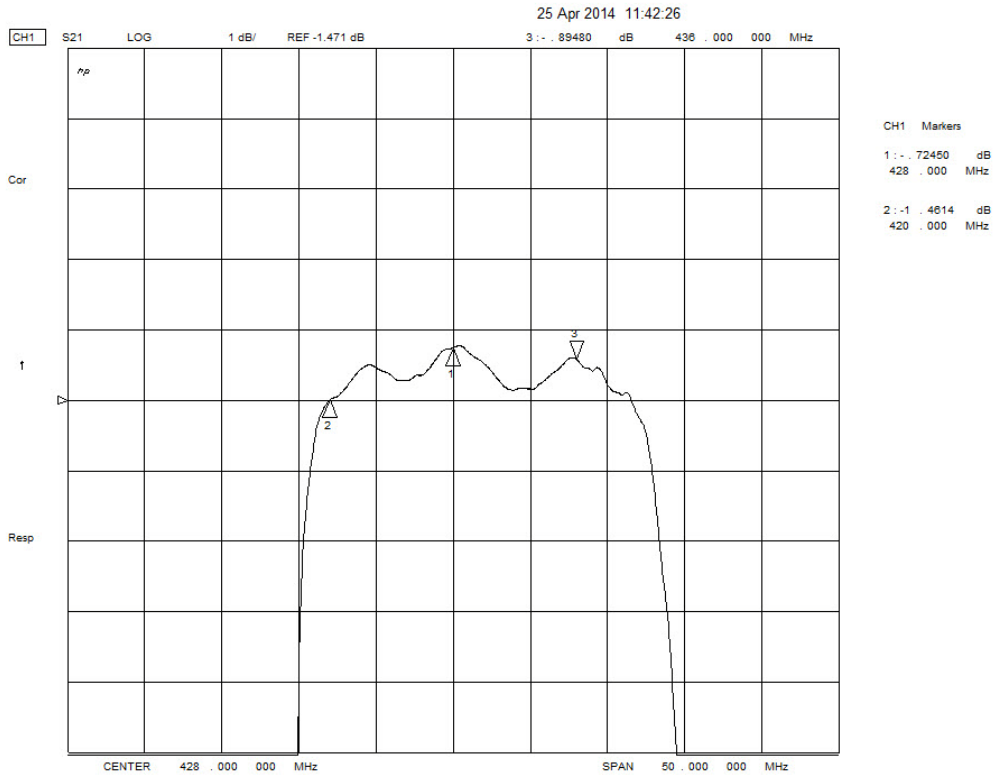


CAUTION: Electrostatic Sensitive Device. Observe precautions for handling.

NOTES:

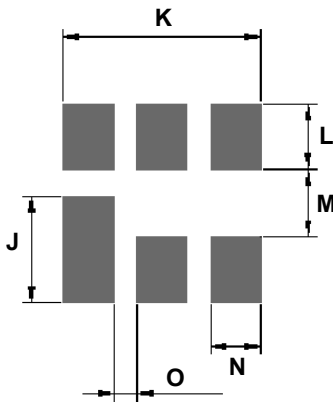
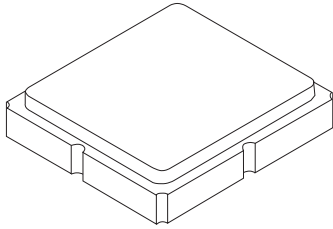
1. The design, manufacturing process, and specifications of this device are subject to change.
2. US or International patents may apply.
3. RoHS compliant from the first date of manufacture.

Frequency Characteristics:



SM3030-6 Case

6-Terminal Ceramic Surface-Mount Case 3.0 X 3.0 mm Nominal Footprint



PCB Footprint

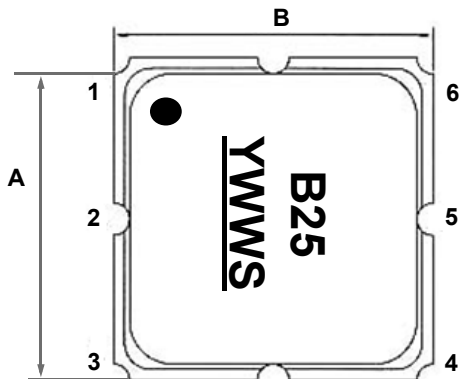
Case and PCB Footprint Dimensions

Dimension	mm			Inches		
	Min	Nom	Max	Min	Nom	Max
A	2.85	3.00	3.15	0.112	0.118	0.124
B	2.85	3.00	3.15	0.112	0.118	0.124
C	-	-	1.40	-	-	0.055
D	2.39	2.54	2.69	0.094	0.100	0.105
E	1.45	1.60	1.75	0.057	0.062	0.068
F	0.70	0.85	0.90	0.027	0.033	0.003
G	1.35	1.50	1.65	0.053	0.059	0.064
H	0.45	0.60	0.75	0.017	0.023	0.029
I	1.15	1.30	1.45	0.045	0.051	0.057
J	-	1.70	-	-	0.066	-
K	-	3.20	-	-	0.125	-
L	-	1.05	-	-	0.041	-
M	-	1.09	-	-	0.042	-
N	-	0.81	-	-	0.031	-
O	-	0.38	-	-	-0.014	-

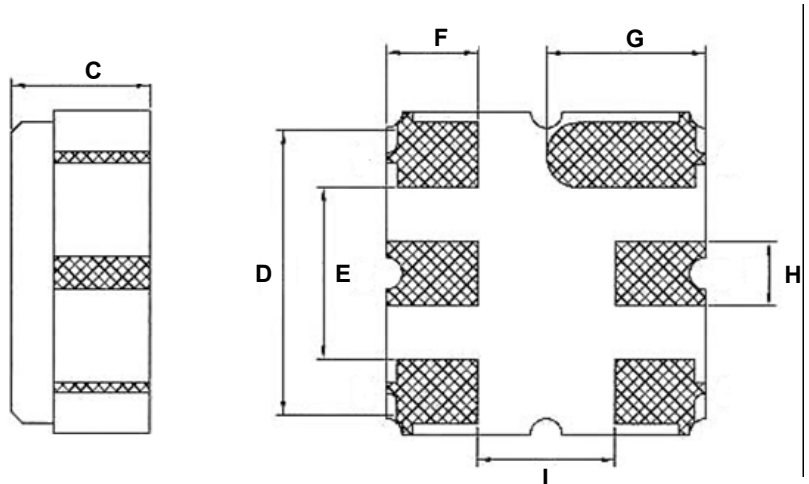
Case Materials

Materials	
Solder Pad Plating	0.3 to 1.0 μm Gold over 1.27 to 8.89 μm Nickel
Lid Plating	2.0 to 3.0 μm Nickel
Body	Al_2O_3 Ceramic

TOP VIEW

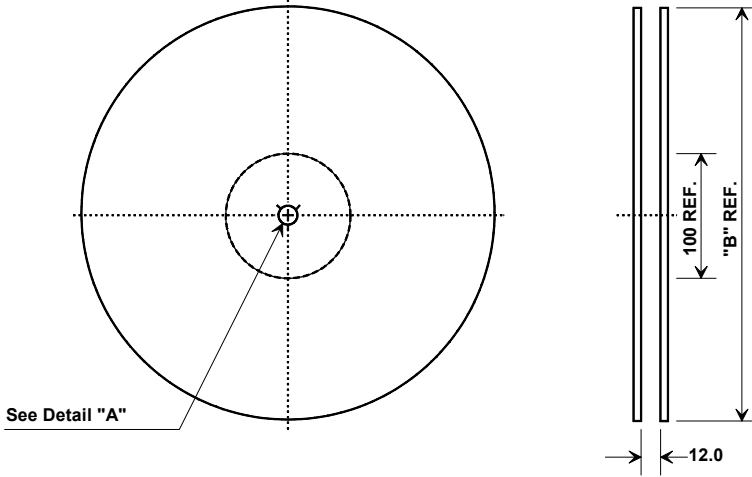


BOTTOM VIEW

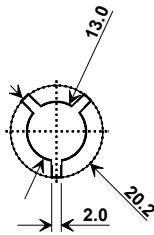


Tape and Reel Specifications

Tape and Reel Standard per ANSI/EIA-481

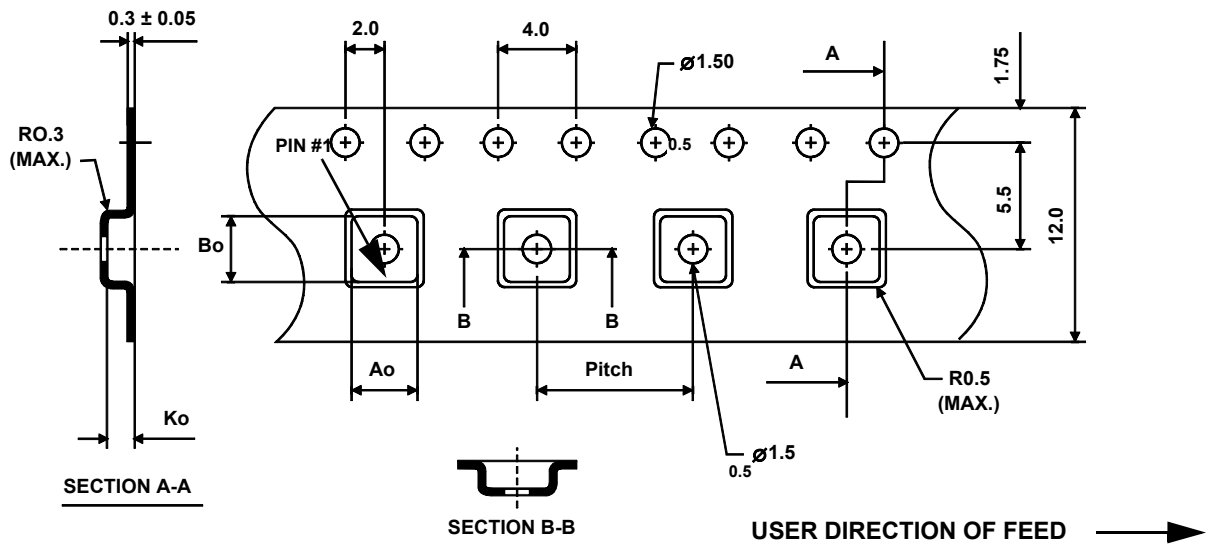


"B"		Quantity Per Reel
Inches	millimeters	
7	178	500
13	330	3000



COMPONENT ORIENTATION and DIMENSIONS

Carrier Tape Dimensions	
Ao	3.35 mm
Bo	3.35 mm
Ko	1.40 mm
Pitch	8.0 mm
W	12.0 mm



Recommended Reflow Profile

1. Preheating shall be fixed at 150~180°C for 60~90 seconds.
2. Ascending time to preheating temperature 150°C shall be 30 seconds min.
3. Heating shall be fixed at 220°C for 50~80 seconds and at 260°C +0/-5°C peak (10 seconds).
4. Time: 5 times maximum.

